

QGel330 Silicone gel tough high purity

Introduction

This is one of a family of soft, adherent, silicone elastomeric gels designed for the encapsulation and protection of electronic components. It is a low viscosity, 2-component system that is readily mixed in a 1:1 ratio. It is used to provide protection from vibration, thermal or mechanical shock and protection from water and many environmental contaminants. It has excellent dielectric properties

Key Features

- Low viscosity
- High purity
- Resilient gel
- Excellent adhesion

Use and Cure Information

IMPORTANT:

The 'A' part of product contains the platinum catalyst; great care should be taken when using automatic dispensing equipment. Please ensure that it is not contaminated by residual hydride containing rubber in the dispensing equipment, as curing will result. If in doubt, it's advised to thoroughly purge the equipment with a suitable hydrocarbon solvent or silicone fluid.

Mixing

Both the 'A' and 'B' parts should be well stirred to ensure the material is uniform and any settled fillers have been remixed. Place the required amount of 'A' and 'B' parts by weight at the mix ratio shown opposite, in a clean plastic or metal container of approximately 3 times their volume, and mix until the colour of the mixture is uniform. For best results, we recommend degassing. Degas by intermittent evacuation, the larger volume of the mixing vessel helps prevent overflow during this operation. In the case of automatic dispensing with static mixing head, the two components should be degassed before processing. Recommended vacuum conditions are 30-50 mbar intermittently over 5-10 minutes. Cast the mixture either by gravity or pressure injection.

Inhibition of Cure

Great care must be taken when handling and mixing all addition cured silicone elastomer systems, ensuring that all the mixing tools (vessels and spatulas) are clean and constructed in materials which do not interfere with the curing mechanism. The cure of the rubber can be inhibited by the presence of compounds of nitrogen, sulphur, phosphorus and arsenic; organotin catalysts and PVC stabilizers; epoxy resin catalysts and even contact with materials containing certain of these substances e.g. moulding clays, sulphur vulcanised rubbers, condensation cure silicone rubbers, onion and garlic.

Curing Conditions

The data offers a guide to the rate of cure at various temperatures, mixing of the components at temperatures between 15 and 25 °C is recommended to ensure adequate pot life for degassing and handling. The pot life can be extended to several hours by chilling the components before mixing.

Health and Safety

Safety Data Sheets available on request.

Packaging

ACC Gels are available in a variety packaging including bulk containers. Please contact our sales department for more information.

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Property

Uncured product

Property	Test Method	Value
Appearance		Clear liquid
Colour A Part		Translucent
Colour B Part		Translucent
Cure Type		Addition
Max Cure Hrs @ 25 °C		20 hrs
Max Cure Mins @ 100 °C		60 mins
Mix Ratio		1:1
Pot Life mins		45 mins
Rheology		Liquid
Self Bonding		Yes
Viscosity A-Part mPas	Brookfield	700 mPas
Viscosity B-Part mPas	Brookfield	650 mPas
Viscosity Mixed mPas	Brookfield	675 mPas

Cured product

After 30 minutes at 150 °C

Property	Test Method	Value
Colour		Transparent
Duro Shore 00	ASTM D 2240-95	38
Max Working Temp + °C	AFS_1540B	200 °C
Min Working Temp - °C		-55 °C
SG	BS ISO 2781	0.97
UL 94V-0		No

Storage

Max storage temperature °C		40 °C
Shelf life		12 mths

Electrical properties

Dielectric Strength kV/mm	ASTM D-149	>18.5 kV/mm
Volume Resistivity ohms cm	ASTM D-257	21.5E+14 ohms cm

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